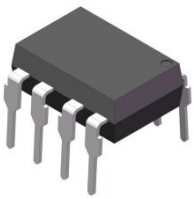
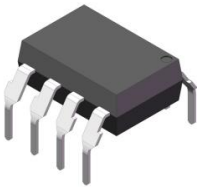
XL2601

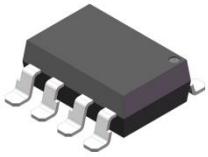
Product packaging logic diagram



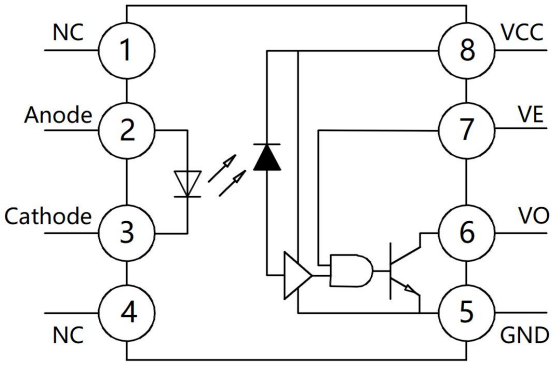
DIP8



DIP8-M



SMD8



Pin Configuration

Features

- Very high speed: 10 MBit/s
- High isolation voltage between input and output (Viso =5000V rms)
- Operating Temperature: -40℃~85℃
- Logic gate output
- Environmentally friendly products, compliant with CQC, UL, and VDE requirements

Mechanical Data

- Case: DIP8、DIP8-M、SMD8
- Molding Compound: UL Flammability Classification Rating 94V-0
- Terminals: Matte tin-plated leads; solder ability-per MIL-STD-202, Method 208

Applications

- Widely used in communications and networking, industrial automation and control, motor drive and energy management, medical equipment, and automotive electronics fields.
- Communications and Networking： Fiber optic communication, data center.

Industrial Automation and Control： PLC and frequency converter, Servo drive system, Industrial robot.

- Motor Drive and Energy Management：Motor control, Motor protection,Power electronics,Consumer Electronics.
- Emerging Technology Fields： Intelligent Transportation System,Medical equipment,Automatic production line.
- Automotive Electronics： In-vehicle Network System,Battery Management System (BMS),EV Charging Station.

Ordering Information

XL	2601	(X)	(X)	(X)	-	(U)	(N)	(Y)
①	②	③	④	⑤		⑥	⑦	⑧

① Brand (XL)

② Product series (2601)

③ Package type (DIP8:None, DIP8-M:M,SMD8:S)

④ Halogen)option (None : Halogen free

⑤ CTR Bank(None)

⑥ Lead frame (None: Copper)

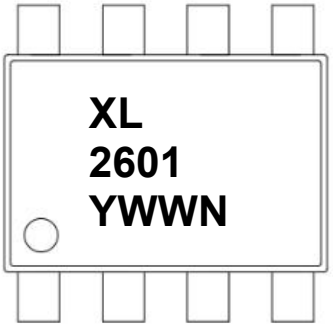
⑦ Customer option 1 (0-9 or A- Z or none)

⑧ Customer option 2 (0-9 or A- Z or none)

Part Number	Package	Shipping Quantity	Marking Code
XL2601	DIP8	45pcs / Tube	XL2601

Marking Information

- " XL" denotes brand
- " 2601" denotes product series:.
- " Y" denotes Year : A(2024), B(2025), C(2026)
- " WW" denotes Week' s number
- " N" denotes the day of Week.



Maximum Ratings (@ T_A = 25°C unless otherwise specified)

Parameter		Symbol	Value	Unit
Input	Forward Current	I_F	50	mA
	Reverse Voltage	V_R	5	V
	Power Dissipation	P_D	100	mW
Output	Collector Output	P_O	85	mW
	Output Current	I_O	50	mA
	Supply Voltage	V_{CC}	7	V
	Output Voltage	V_O	7	V

Thermal Characteristics

Parameter	Symbol	Value	Unit
Isolation Voltage *2	V_{ISO}	5000	Vrms
Operating Temperature	T_{OPR}	-40 ~ +85	°C
Storage Temperature Range	T_{STG}	-55 ~ +125	°C
Soldering Temperature *3	T_{SOL}	260	°C

Notes:

1. Pulse width≤1μs, Duty ratio: 0.001
2. 40 to 60% RH, AC for 1 minute
3. For 10 seconds

Electrical Characteristics (@ T_A = 25°C unless otherwise specified)

Parameter		Symbol	Test Condition	Min.	Typ.	Max.	Unit
Input	Forward Voltage	V_F	I_F = 10mA	-	1.33	1.75	V
	Reverse Breakdown Voltage	B_{VR}	I_R=10μA	5	-	-	V
	Capacitance	C_{in}	V_R = 0V, f = 1MHz	-	70	-	pF
	Diode Temperature Coefficient	$\Delta V_F/\Delta T_A$	I_F=10mA	-	-1.4	-	mV/°C
Output	High Level Supply Current	I_{CCH}	V_{CC}=5.5V,I_F=0mA V_E=0.5V	-	6.5	10	mA
	Low Level Supply Current	I_{CCL}	V_{CC}=5.5V, I_F=10mA	-	9	13	mA
	Low Level Enable Current	I_{EL}	V_{CC}=5.5V, V_E=0.5V		-0.8	-1.6	mA
	High Level Enable Current	I_{EH}	V_{CC}=5.5V, V_E=2.0V		-0.6	-1.6	mA
	High Level Enable Voltage	V_{EH}	V_{CC}=5.5V, I_F=10mA	2.0			V
	Low Level Enable Voltage	V_{EL}	V_{CC}=5.5V, I_F=10mA			0.8	V
Transfer Characteristics	High Level Output Current	I_{OH}	V_{CC}=5.5V, V_O=5.5V I_F= 250μA , V_E=2V	-	-	100	μA
	Low Level Output Voltage	V_{OL}	V_{CC}=5.5V, I_F=5mA I_{CL}=13mA,V_E=2V	-	0.35	0.6	V
	Input Threshold Current	I_{FT}	V_{CC}=5.5V, V_O=0.6V I_{OL}=13mA,V_E=2V	-	3	5	mA
	Isolation Resistance	R_{IO}	V_{IO} = 500Vdc 40~60% R.H.	1×10^{12}	-	-	Ω
	Floating Capacitance	C_{IO}	f = 1MHz	-	0.6	-	pF

Switching Characteristics (@ T_A = -40°C～85°C, V_{CC}= 5V, I_F= 7.5mA, unless otherwise specified)

Parameter	Symbol	Test Condition	Min.	Typ.	Max.	Unit
Propagation Delay Time to Output HIGH Level	T_{PLH}	C_L=15pF R_L=350Ω T_A=25°C	20	41	100	ns
Propagation Delay Time to Output Low Level	T_{PHL}		25	50	100	ns
Pulse Width Distortion	$\|T_{PHL}-T_{PLH}\|$		-	5	35	ns
Output Rise Time (10–90%)	t_r		-	30	-	ns
Output Rise Time (90–10%)	t_f		-	10	-	ns
Enable Propagation Delay Time to Output HIGH Level	t_{ELH}	I_F=7.5mA, V_{EH}=3.5V R_L=350Ω, C_L=15pF		15		ns
Enable Propagation Delay Time to Output LOW Level	t_{EHL}			40		ns
Common Mode Transient Immunity (at Output HIGH Level)	$\|CM_H\|$	T_A=25°C,I_F=0mA $\|V_{CM}\|$=50V(Peak) V_{OH}=2.0V,R_L=350Ω	5000	10000	-	V/μs
Common Mode Transient Immunity (at Output LOW Level)	$\|CM_L\|$	$_F$=7.5mA, V_{OL}=0.8V R_L=350Ω, T_A=25°C	5000	10000	-	V/μs

Ratings and Characteristics Curves (@ T_A = 25°C unless otherwise specified)

Fig.1 Forward Current vs. Forward Voltage

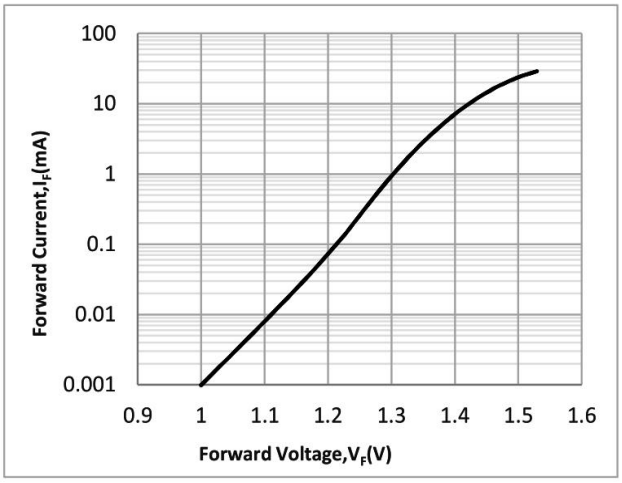


Fig.2 Low Level Output Voltage vs. Ambient Temperature

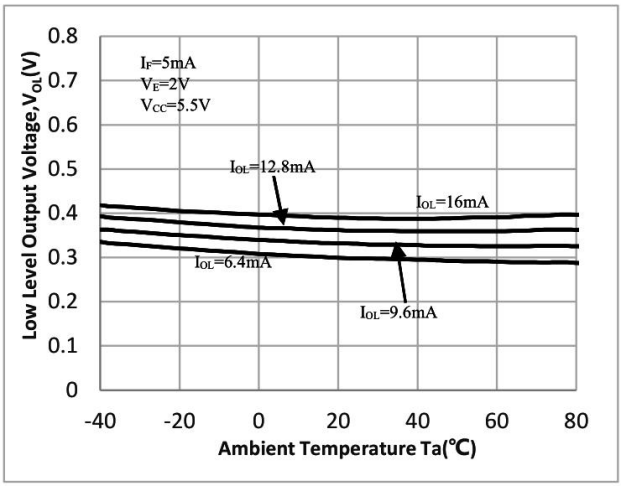


Fig.3 Switching time vs. Forward Current

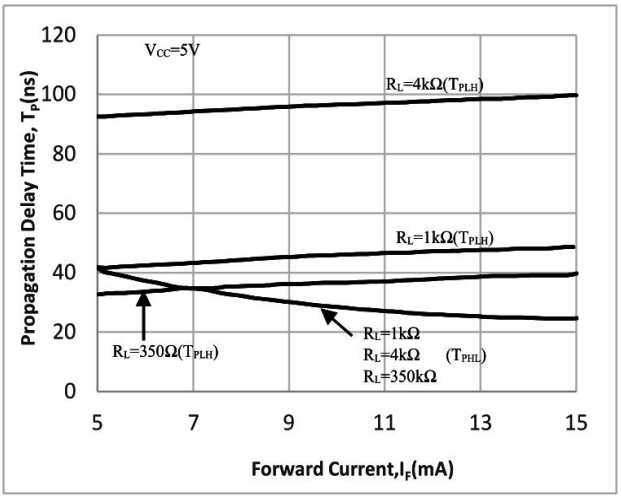


Fig4 Low Level Output Current vs. Ambient Temperature

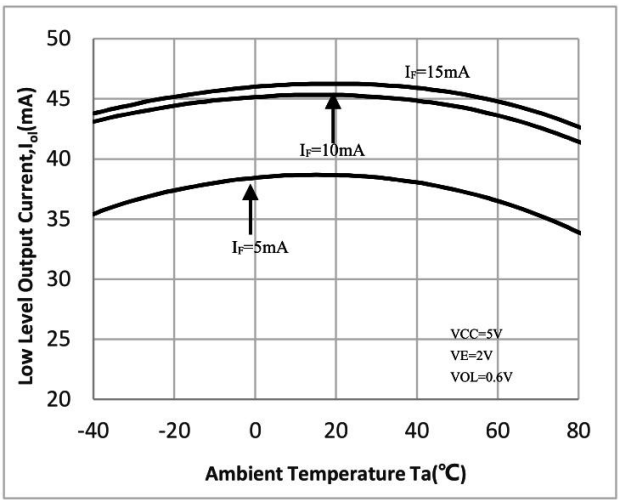


Fig.5 Start Current vs. Ambient Temperature

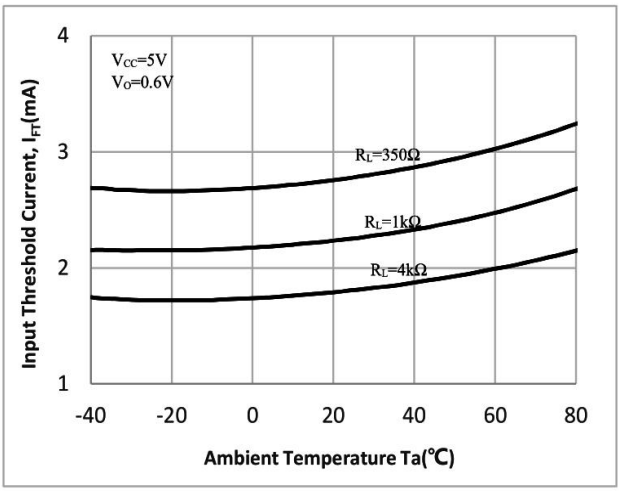
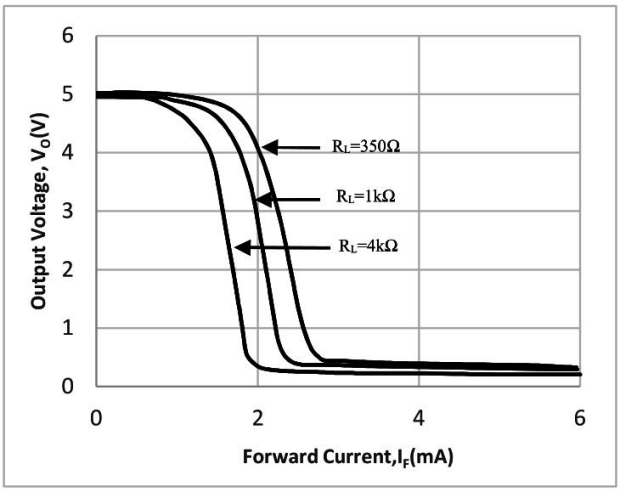


Fig.6 Output Voltage vs. Input Forward Current



Ratings and Characteristics Curves (@ T_A = 25°C unless otherwise specified)

Fig.7 Pulse Width Distortion vs. Ambient Temperature

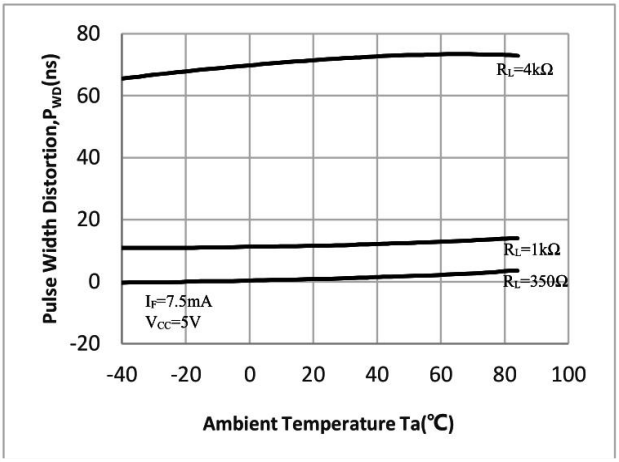


Fig.8 Rase and Fall Time vs. Ambient Temperature

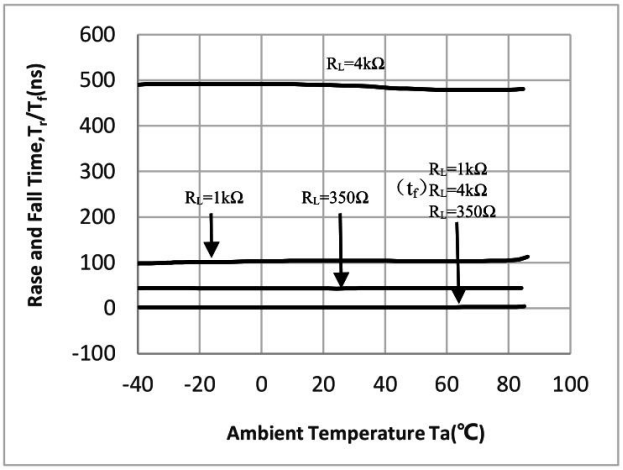
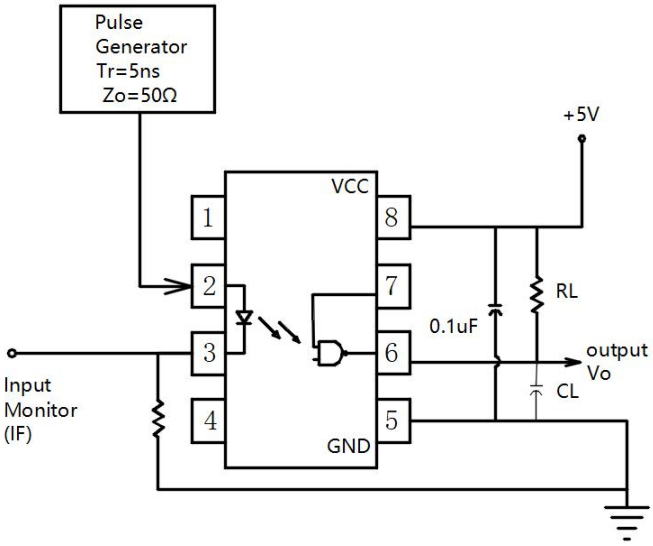


Fig.9 Test Circuit and Wave forms for t_{PLH}, t_{PHL}, t_r and t_f



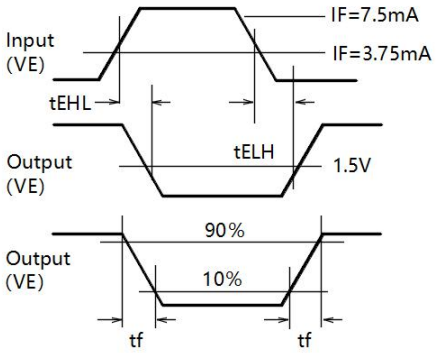
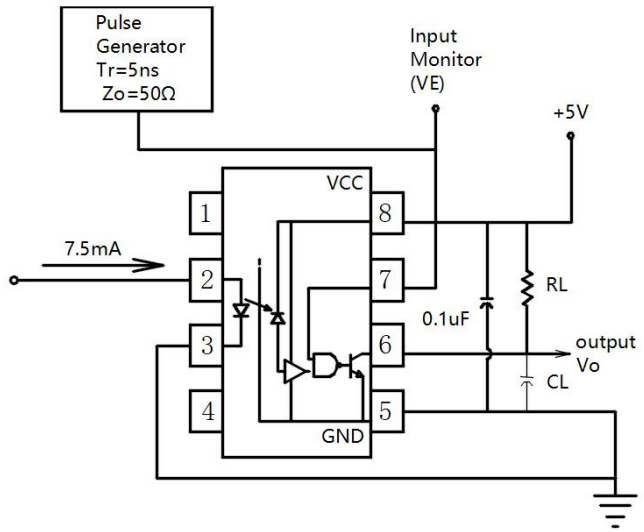


Fig.10 Test Circuit t_{EHL} and t_{ELH}



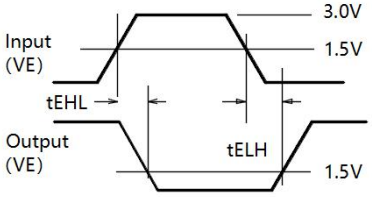
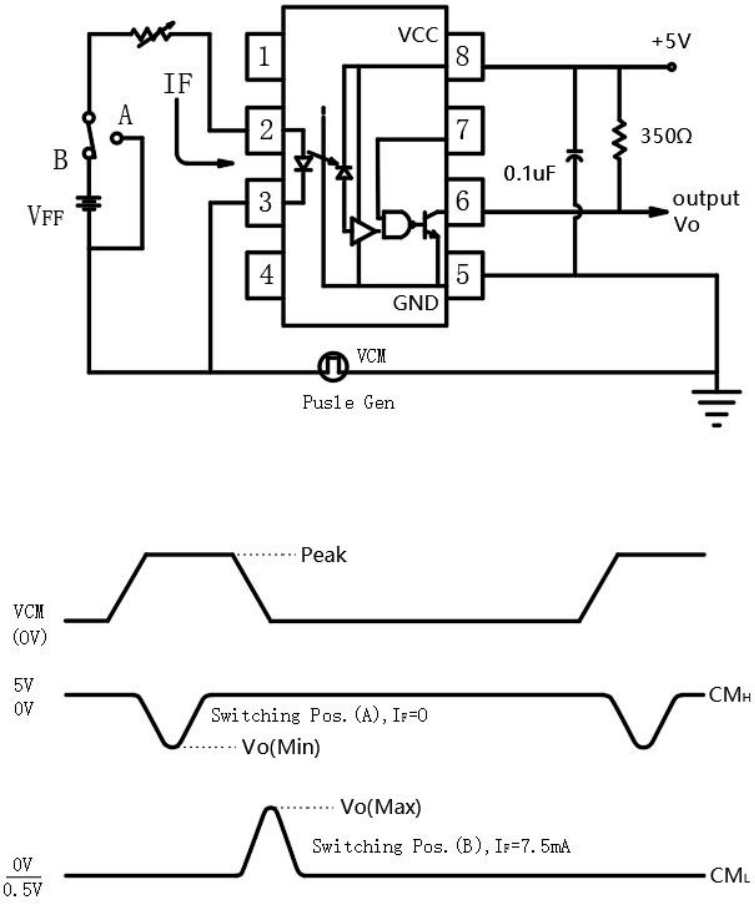
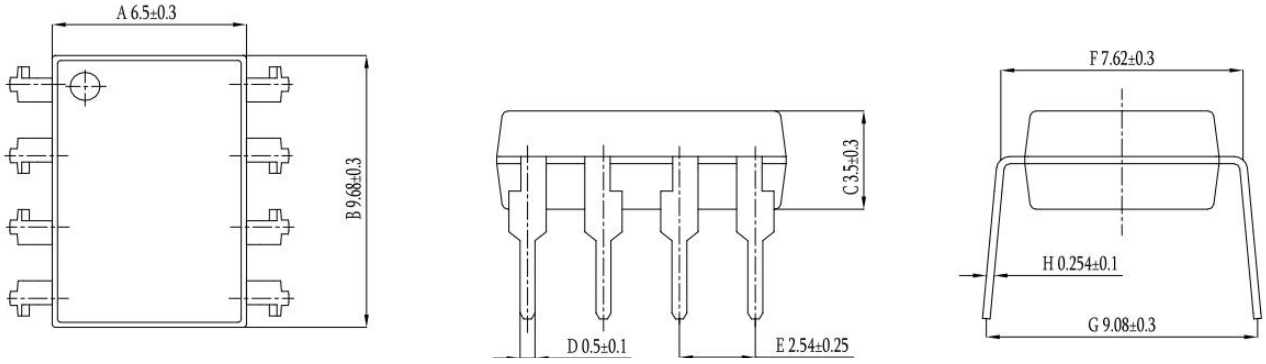


Fig.11 Test Circuit Common Mode Transient Immunity

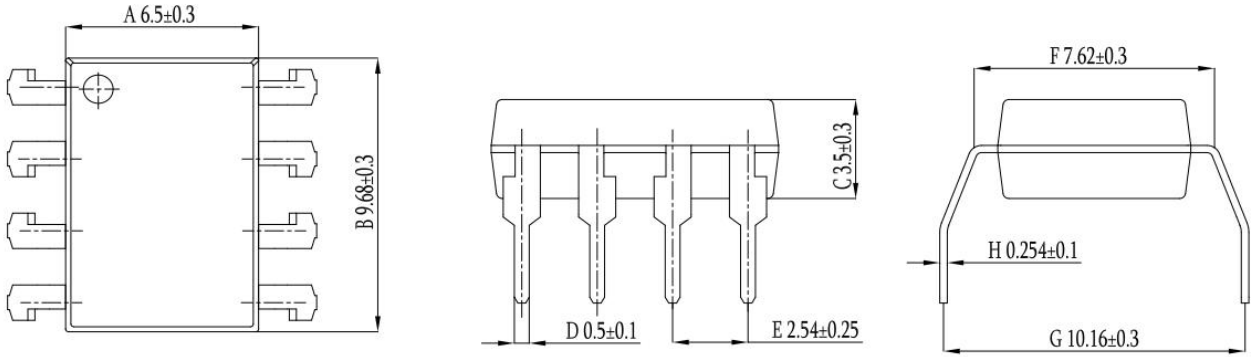


Package Outline Dimensions (unit: mm)

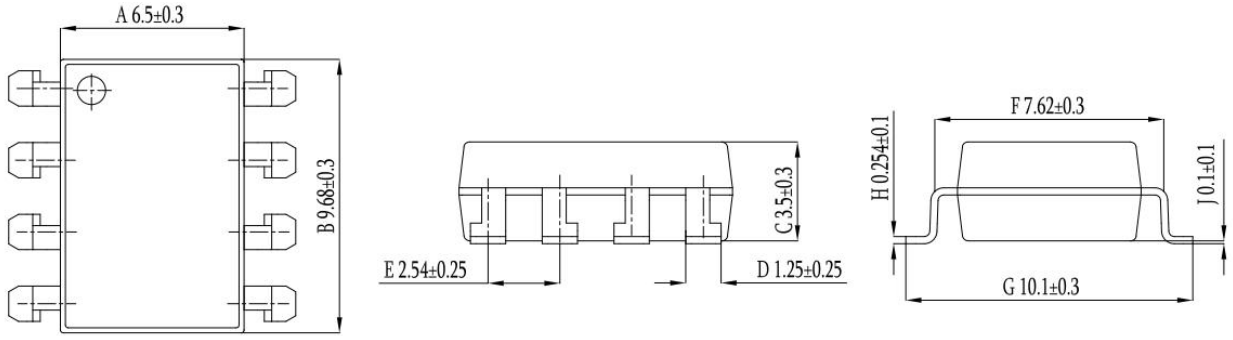
DIP8



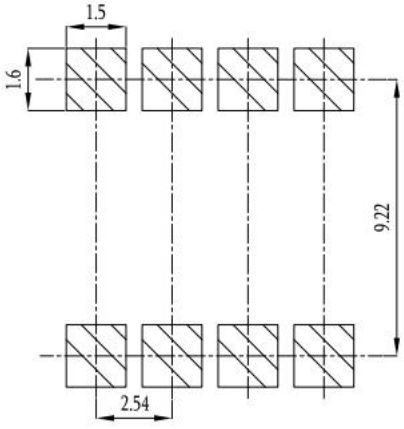
DIP8-M



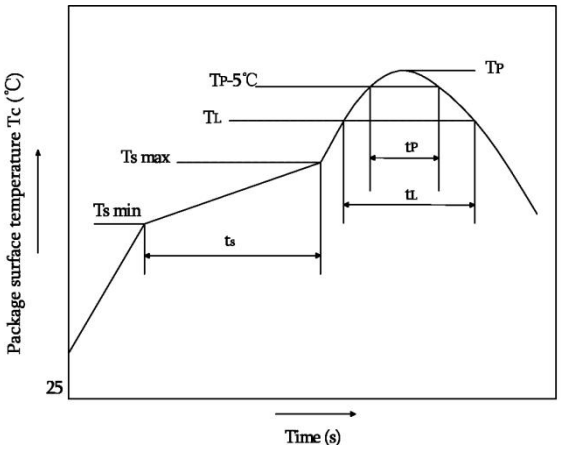
SMD8



SOLDERING FOOTPRINT (unit: mm)



Reflow soldering

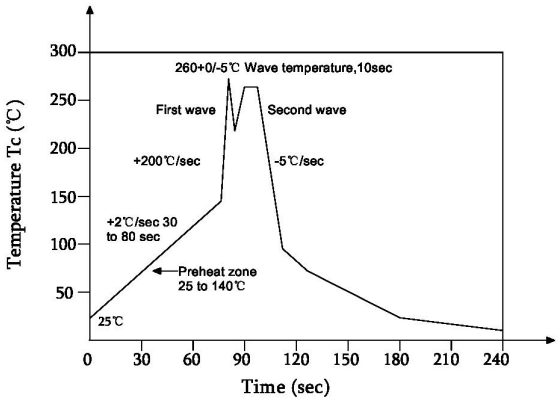


	Symbol	Min	Max	Unit
Preheat temperayure	Ts	150	200	℃
Preheat time	ts	60	120	s
Ramp-up ratea(T_L to T_P)			3	℃/s
Liquidus temperature	T_L	217		℃
Time above T_L	t_L	60	150	s
Peak temperature	Tp		260	℃
Time during which Tc is between (T_P-5) and T_P	t_p		30	s
Ramp-down rate(T_P to T_L)			6	℃/s

Note:

Reflow soldering is recommended at the temperatures and times shown, no more than three times.

Wave soldering



Profile feature	
Average ramp-up rate	~200℃/s
Heating rate during preheat	1℃/s to 2℃/s typical;4℃/s maximum
Final preheat temperature Ts	~130℃
Preheat time (25℃ to Ts)	>60s
Peak temperature Tp	260℃
Time within peak temperature tp	10s
Ramp-down rate	5℃/s maximum

Soldering with hand soldering iron

A. Hand soldering iron is only used for product rework or sample testing.

B. Hand soldering iron requirements:Temperature:360 ℃+5℃ within 3s.

Packing

Package Type	Packing Form	Quantity per Tube &Reel	Quantity per Box	Quantity per Carton	Antistatic Bag Specification	Box Specification	Carton Specification	Note
DIP8	Tube(500mm)	45pcs/tube	50 tubes /box	10 boxes /ctn	190*670mm	520*105*50mm	545*372*235mm	Straight insert type material tube
DIP8-M	Tube(500mm)	45pcs/tube	50 tubes /box	10 boxes /ctn	190*670mm	520*105*50mm	545*372*235mm	Seagull foot (M foot) tube
SMD8	Reel(ϕ330mm)	1000pcs/reel	2 reels /box	10 boxes /ctn	380*420mm	350*340*60mm	365*330*370mm	Guard band 200mm /min.

■ Summary table

■ DIP8/DIP8-M（Tube）

Qty/tube：45pcs.　Qty/box：2250pcs.

Qty/ctn：22500pcs.

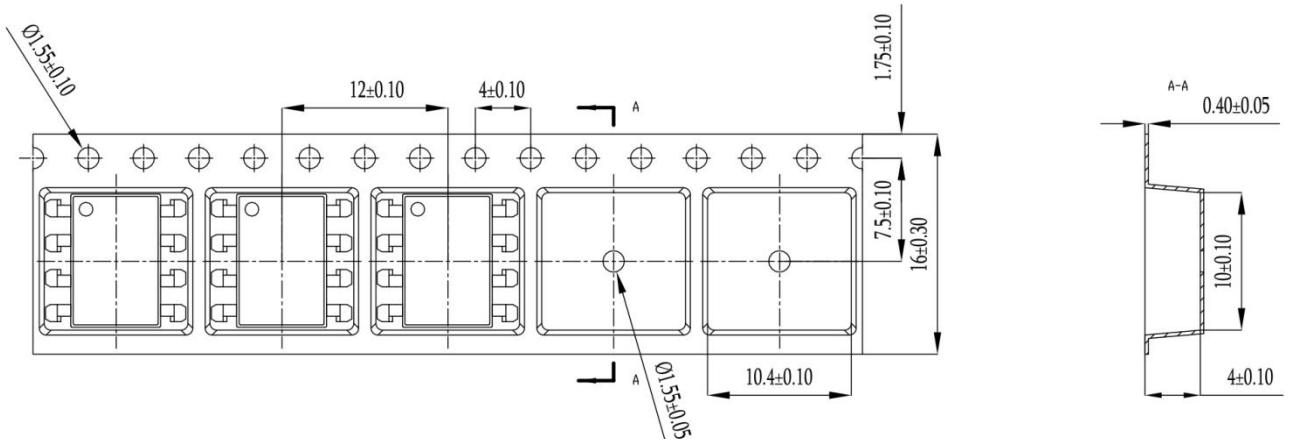
Schematic：（unit：mm）

■ SMD8（Reel）

Qty/reel：1000pcs.　Qty/box：2000pcs.

Qty/ctn：20000pcs.

Schematic：（unit：mm）



Attention

■ XINGLIGHT　implements dynamic technical updates. Specifications are subject to change. Refer to the official website for the latest version.

■ Users must strictly adhere to specified conditions. Failures caused by misuse (overload, high temperature, incompatible circuits) are excluded from warranty.

■ Contact technical support for customized validation in critical applications (medical devices, industrial control).

■ This document is valid until Dec 31, 2026. Updates will be notified on the official website.

■ For further clarification on technical specifications or application solutions, please contact us through official channels.